



Material Content Data Sheet



Sales Product Name				IPD088N06N3 G		Issued		20. July 2018	
MA#				MA000473316					
Package				PG-TO252-3-311		Weight*		316.17 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.120	0.67	0.67	6705	6705	
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		453		
	inorganic material	phosphorus	7723-14-0	0.043	0.01		136		
	non noble metal	copper	7440-50-8	143.098	45.25	45.31	452600	453189	
wire	non noble metal	aluminium	7429-90-5	21.133	6.68	6.68	66842	66842	
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.741	0.55		5508		
	plastics	brominated resin	-	1.866	0.59		5901		
	organic material	carbon black	1333-86-4	1.990	0.63		6295		
	plastics	epoxy resin	-	16.792	5.31		53110		
	inorganic material	silicondioxide	60676-86-0	101.994	32.26	39.34	322594	393408	
leadfinish	non noble metal	tin	7440-31-5	3.787	1.20	1.20	11977	11977	
plating	non noble metal	nickel	7440-02-0	0.086	0.03		273		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	274	
solder	noble metal	silver	7440-22-4	0.054	0.02		172		
	non noble metal	tin	7440-31-5	0.043	0.01		137		
	non noble metal	lead	7439-92-1	2.074	0.66	0.69	6561	6870	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		61		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.07	6.08	60656	60735	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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